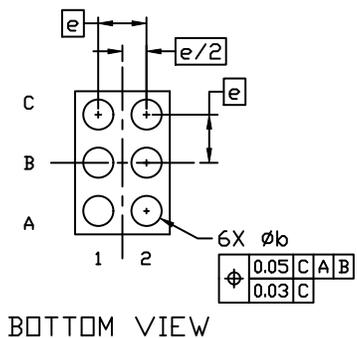
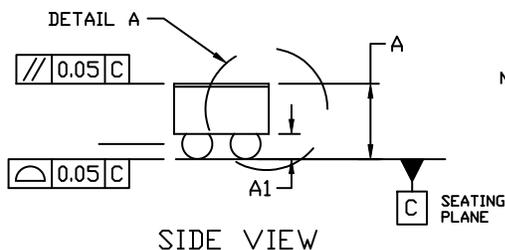
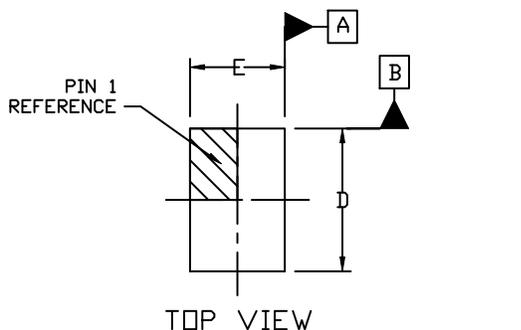




**WLCSP6 1.2x0.8x0.62**  
**CASE 567WQ**  
**ISSUE O**

DATE 27 JUN 2018



**GENERIC MARKING DIAGRAM\***

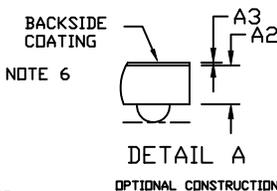


X = Specific Device Code  
 Y = Year  
 W = Work Week

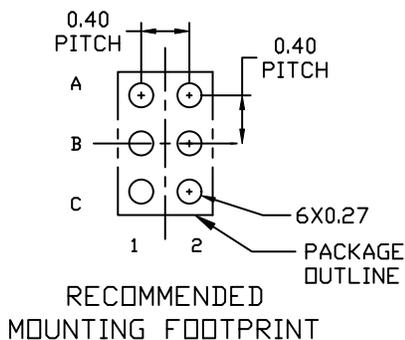
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.62
A1	0.16	0.195	0.23
A2	0.35 REF		
A3	0.025 REF		
b	0.24	0.27	0.30
D	1.18	1.20	1.22
E	0.78	0.80	0.82
e	0.40 BSC		



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<b>DESCRIPTION:</b>	<b>WLCSP6 1.2x0.8x0.62</b>	<b>PAGE 1 OF 1</b>

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